

FRANKEN ET AL. - 10/615,421  
Client/Matter: 081468-0304791

IN THE SPECIFICATION:

Page 1, just below the title, please insert the following:

This application claims priority to European Patent Application 02254863.0, filed July 11, 2002, the contents of which are incorporated by reference.

Page 3, delete the whole paragraph starting in line 27 and replace it with the following new paragraph:

For the sake of simplicity, the projection system may hereinafter be referred to as the "lens." However, this term should be broadly interpreted as encompassing various types of projection system, including refractive optics, reflective optics, and catadioptric systems, for example. The radiation system may also include components operating according to any of these design types for directing, shaping or controlling the projection beam of radiation, and such components may also be referred to below, collectively or singularly, as a "lens". Further, the lithographic apparatus may be of a type having two or more substrate tables (and/or two or more mask tables). In such "multiple stage" devices the additional tables may be used in parallel or preparatory steps may be carried out on one or more tables while one or more other tables are being used for exposures. Dual stage lithographic apparatus are described, for example, in U.S. Patent Patents 5,969,441 and ~~WO 98/40794~~ 6,262,796.

Page 5, delete the whole paragraph starting in line 17 and replace it with the following new paragraph:

This and other aspects are achieved according to the present invention in a lithographic apparatus including a radiation system constructed and arranged to provide a ~~projection~~ beam of radiation; a support ~~structure~~ constructed and arranged to support a patterning device, the patterning device constructed and arranged to pattern the projection beam according to a desired pattern; a substrate table constructed and arranged to hold a substrate; a projection system constructed and arranged to project the patterned beam onto a target portion of the substrate; a base to which the support ~~structure~~ and the substrate table are

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mounted; and a reference frame, compliantly mounted to the base, wherein the projection system comprises at least one optical element mounted on a projection frame that is compliantly mounted to the reference frame.

Page 6, delete the whole paragraph starting in line 17 and replace it with the following new paragraph:

According to a further aspect of the invention there is provided a device manufacturing method including ~~providing a substrate that is at least partially covered by a layer of radiation-sensitive material;~~ projecting a patterned beam of radiation onto a target portion of ~~[[the]]~~ a layer of radiation-sensitive material at least partially covering a substrate using a projection system; supporting a reference frame, a support ~~structure~~ constructed and arranged to support a patterning device and a substrate table constructed and arranged to hold the substrate on a base, wherein the reference frame is compliantly mounted to the base and the projection system is mounted to the reference frame; and compliantly mounting the projection system to the reference frame while projecting the patterned beam of radiation onto the target portion.

Page 8, delete the whole paragraph starting in line 3 and replace it with the following new paragraph:

Figure 1 schematically depicts a lithographic projection apparatus 1 according to an embodiment of the invention. The apparatus 1 includes a base BP; a radiation system Ex, IL constructed and arranged to supply a ~~projection~~ beam PB of radiation (e.g. EUV radiation), which in this particular case also comprises a radiation source LA; a first object (mask) table MT provided with a mask holder constructed and arranged to hold a mask MA (e.g. a reticle), and connected to a first positioning device PM that accurately positions the mask with respect to a projection system or lens PL; a second object (substrate) table WT provided with a substrate holder constructed and arranged to hold a substrate W (e.g. a resist-coated silicon wafer), and connected to a second positioning device PW that accurately positions the substrate with respect to the projection system PL. The projection system or

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lens PL (e.g. a mirror group) is constructed and arranged to image an irradiated portion of the mask MA onto a target portion C (e.g. comprising one or more dies) of the substrate W.

Page 8, delete the whole paragraph starting in line 20 and replace it with the following new paragraph:

The source LA (e.g. a discharge or laser-produced plasma source) produces a beam of radiation. This beam radiation is fed into an illumination system (illuminator) IL, either directly or after having traversed a conditioning device, such as a beam expander Ex, for example. The illuminator IL may comprise an adjusting device AM that sets the outer and/or inner radial extent (commonly referred to as  $\sigma$ -outer and  $\sigma$ -inner, respectively) of the intensity distribution in the beam. In addition, it will generally comprise various other components, such as an integrator IN and a condenser CO. In this way, the beam PB impinging on the mask MA has a desired uniformity and intensity distribution in its cross-section.